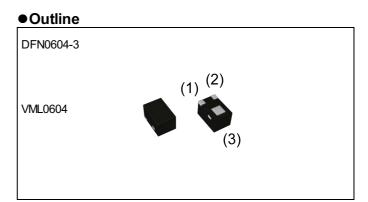
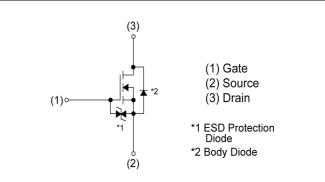


Nch 20V 150mA Small Signal MOSFET

V _{DSS}	20V
R _{DS(on)} (Max.)	2.0Ω
I _D	±150mA
P _D	100mW



Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Basic ordering unit (pcs)	8000
	Taping code	T2CL
	Marking	RY

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

e tu			
Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	20	V
Continuous drain current	۱ _D *1	±150	mA
Pulsed drain current	I _{DP} *2	±600	mA
Gate - Source voltage	V _{GSS}	±10	V
Power dissipation	P _D *3	100	mW
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

•Features

- 1) Ultra Small Package (0.6×0.4×0.36mm)
- 2) Low voltage drive (1.5V) makes this device
- ideal for portable equipment.

Application

Switching

Level shifter

- 3) Drive circuits can be simple.
- 4) Built-in ESD Protection Diode.

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•Thermal resistance

Parameter	Symbol	Values			Linit
Farameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	R_{thJA}^{*3}	-	-	1250	°C/W

•Electrical characteristics (T_a = 25°C)

Deremeter	Currente e l	Canditiana	Values			l leit	
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 1mA	20	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	I _D = 1mA referenced to 25°C	-	29	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 20V, V _{GS} = 0V	-	-	1	μA	
Gate - Source leakage current I_{GSS} $V_{GS} = \pm 8V, V_{DS} = 0V$		V_{GS} = ±8V, V_{DS} = 0V	-	-	±10	μA	
		V _{DS} = 10V, I _D = 100µA	0.3	-	0.8		
Gate threshold voltage	$V_{GS(th)}$	V _{DS} = 10V, I _D = 100µA T _a = -25°C	-	-	0.840	V	
Gate threshold voltage temperature coefficient $\Delta V_{GS(th)}$ ΔT_j $I_D = 1mA$ referenced to 25°C		-	-1.6	-	mV/°C		
		V _{GS} = 4.5V, I _D = 150mA	-	1.4	2.0		
Static drain - source on - state resistance	R _{DS(on)} *4	V _{GS} = 2.5V, I _D = 150mA	-	1.7	2.6	Ω	
		V _{GS} = 1.5V, I _D = 20mA	-	2.7	5.4		

*1 Limited only by maximum temperature allowed.

*2 Pw \leq 10µs , Duty cycle \leq 1%

*3 Each therminal mounted on a reference land

*4 Pulsed



• Electrical characteristics ($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions	Values			Unit	
	Symbol Conditions –		Min.	Тур.	Max.	Unit	
Input capacitance	C _{iss}	V _{GS} = 0V	-	12	-		
Output capacitance	C _{oss}	V _{DS} = 10V	-	5	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	3	-		
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 10 \text{V}, \text{V}_{GS} = 4.5 \text{V}$	-	3	-		
Rise time	t _r *4	I _D = 75mA	-	4	-	20	
Turn - off delay time	$t_{d(off)}^{*4}$	$R_L \simeq 133\Omega$	-	12	-	ns	
Fall time	t _f *4	R _G = 10Ω	-	25	-		

• Body diode electrical characteristics (Source-Drain) ($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions	Values			Unit
	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	۱ _S *1	$T = 25^{\circ}$	-	-	80	mA
Pulse forward current	I_{SP}^{*2}	T _a = 25℃	-	-	600	mA
	V _{SD} *4	V _{GS} = 0V, I _S = 150mA	-	-	1.2	
Forward valtage		V _{GS} = 0V, I _S = 1mA	-	-	0.800	V
Forward voltage		V _{GS} = 0V, I _S = 1mA T _a = -25°C	-	-	0.900	V



RV3C002UN

•Electrical characteristic curves

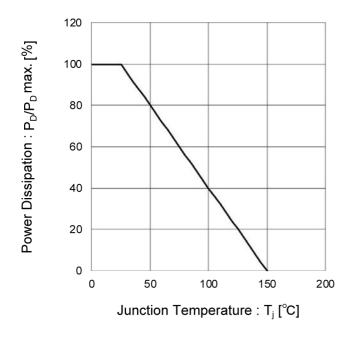


Fig.1 Power Dissipation Derating Curve

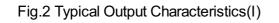
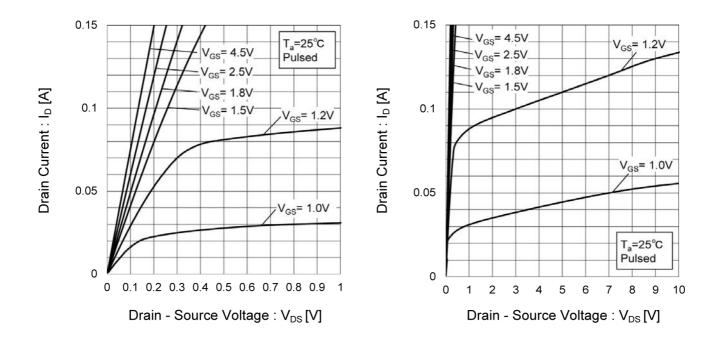


Fig.3 Typical Output Characteristics(II)





 $V_{GS} = 0V$ $I_D = 1mA$ Pulsed

-25

0

25



Fig.4 Breakdown Voltage vs. Junction Temperature

Fig.5 Typical Transfer Characteristics

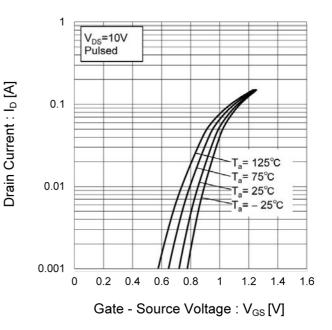


Fig.6 Gate Threshold Voltage vs. Junction Temperature

50

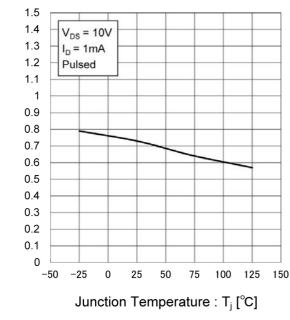
Junction Temperature : T_j [°C]

75

100 125

150

Gate Threshold Voltage : $V_{GS(th)}$ [V]





• Electrical characteristic curves

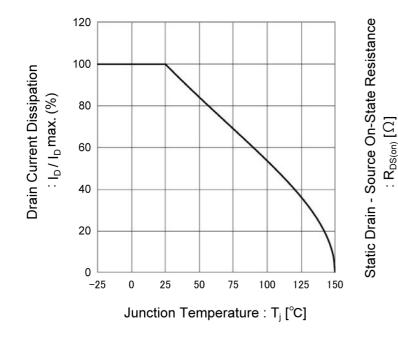


Fig.7 Drain Current Derating Curve

Fig.8 Static Drain - Source On - State Resistance vs. Gate Source Voltage

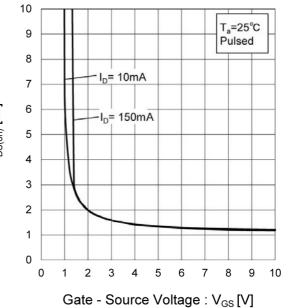
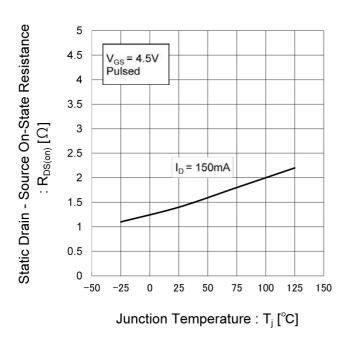


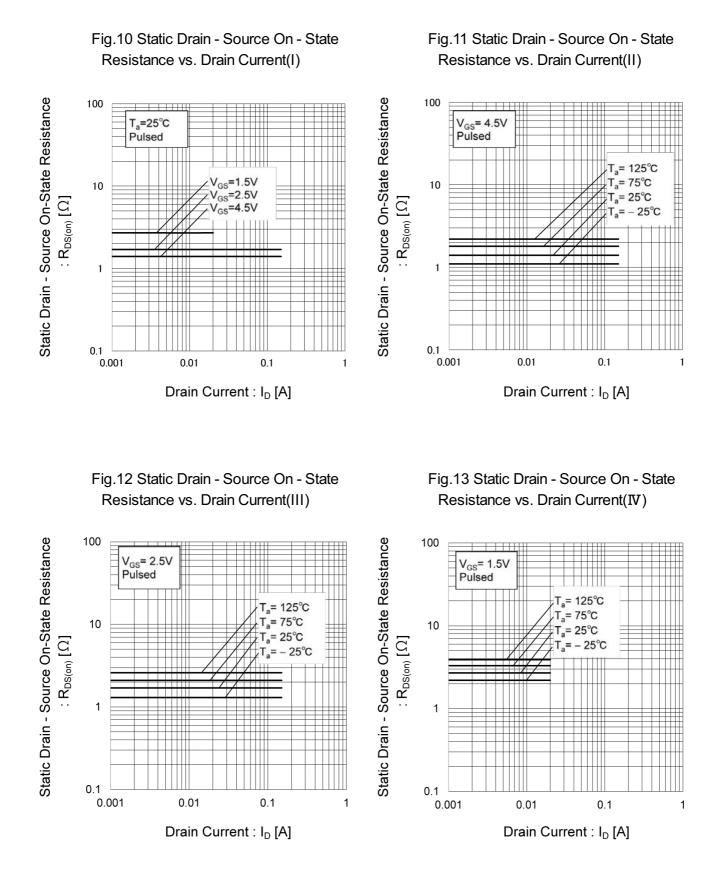
Fig.9 Static Drain - Source On - State Resistance vs. Junction Temperature







•Electrical characteristic curves







Capacitance : C [pF]

• Electrical characteristic curves

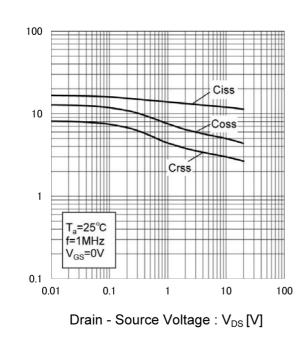
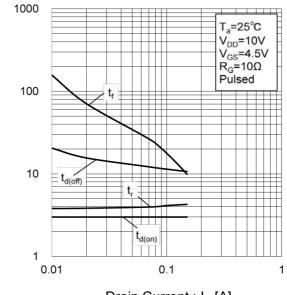


Fig.14 Typical Capacitance vs. Drain -Source Voltage

Switching Time : t [ns]

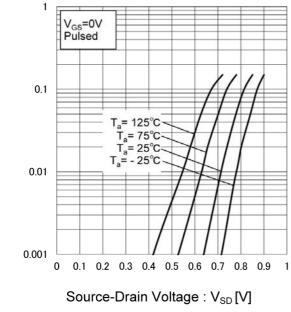
Fig.15 Switching Characteristics



Drain Current : I_D [A]

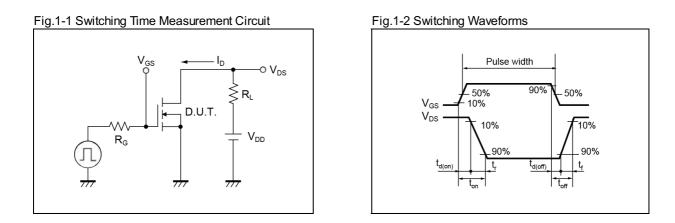
Fig.16 Source Current vs. Source Drain Voltage

Source Current :I_s[A]





• Measurement circuits

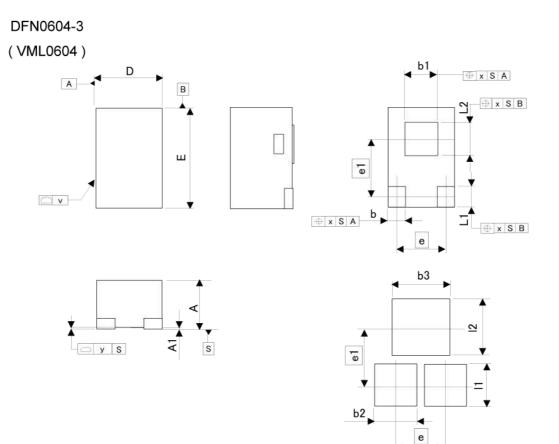


Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM -	MILIMETERS		INCHES		
	MIN	MAX	MIN	MAX	
A	0.33	0.39	0.013	0.015	
A1	0.00	0.05	0.000	0.002	
b	0.05	0.15	0.002	0.006	
b1	0.15	0.25	0.006	0.010	
D	0.35	0.45	0.014	0.018	
E	0.55	0.65	0.022	0.026	
е	0.	30	0.0).012	
e1	0.	35	0.014		
L1	0.07	0.17	0.003	0.007	
L2	0.15	0.25	0.006	0.010	
x	5 .	0.10	(H)	0.004	
У	3 - X	0.10		0.004	
v	-	0.05		0.002	

	MILIME	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	2 1 2	0.25		0.010
b3	<u>a</u>	0.35		0.014
11	7 2	0.27		0.011
12	-	0.35		0.014

Dimension in mm/inches



Notice

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	CLASSⅣ	CLASSIL	CLASSⅢ	CLASSI

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 - [a] Installation of protection circuits or other protective devices to improve system safety
 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

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